

PROC121 - HSE - NAND EXPANSION BOARD

TMDS64DC02EVM

TABLE OF CONTENTS

PAGE	CONTENTS
1	TABLE OF CONTENTS
2	REVISION HISTORY
3	BLOCK DIAGRAM
4	HSE CONNECTOR
5	PRG SIGNAL HEADERS
6	GPMC MUX AND NAND FLASH
7	HARDWARE SCHEMATIC
8	
9	
10	
11	
12	

REV	E1
VER	0.1

Designed for TI by Mistral Solutions Pvt Ltd



Title: TABLE OF CONTENTS

Size	Variant Name = TMDS64DC02EVM	Rev
C		E1
Date:	Tuesday, June 29, 2021	Sheet 1 of 7

REVISION HISTORY

REV #	VER #	DATE	DESCRIPTION OF CHANGES	AUTHOR	REVIEWED BY	APPROVED BY
E1	0.1	24-06-2021	Draft Schematics	Mistral Design Team	RAKESH RAJDEV	AJIT MB

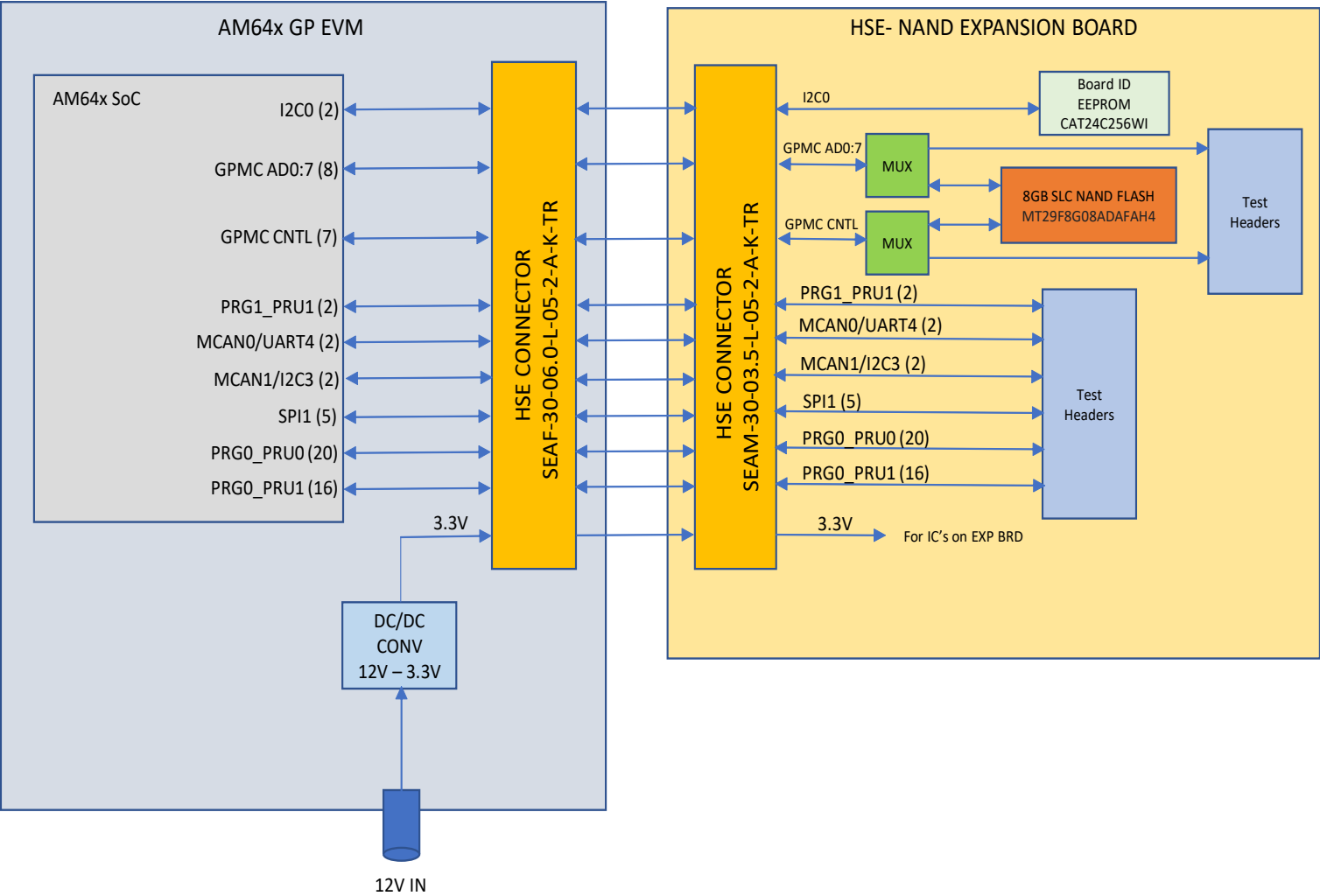
Designed for TI by Mistral Solutions Pvt Ltd



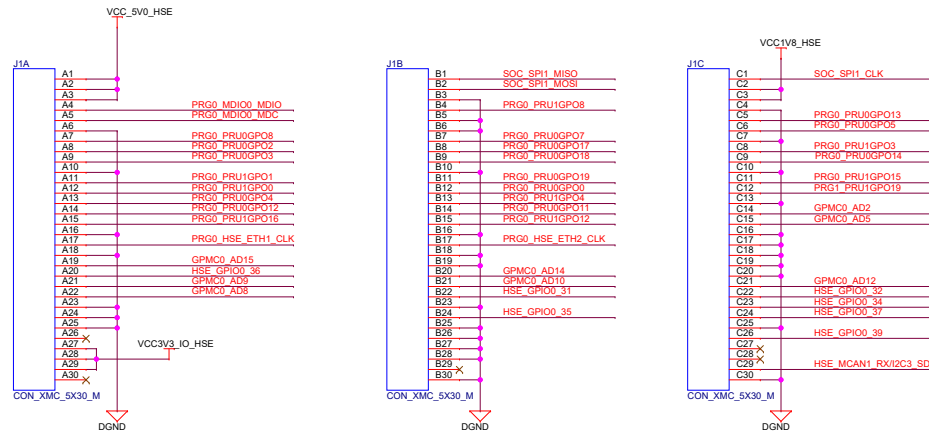
Title REV HISTORY

Size	Variant Name = TMD64DC02EVM		Rev
C			E1
Date:	Tuesday, June 29, 2021	Sheet 2 of 7	

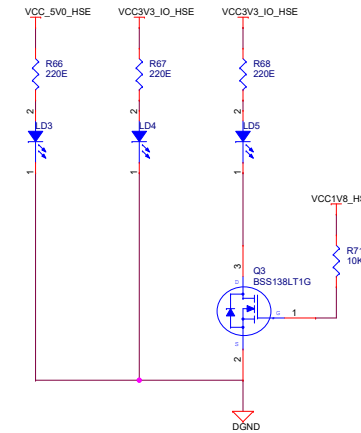
BLOCK DIAGRAM



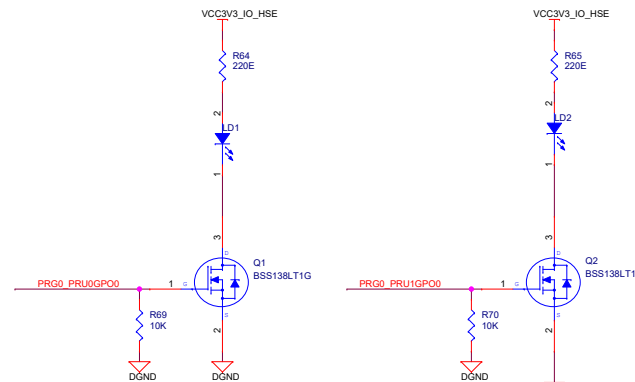
HSE CONNECTOR



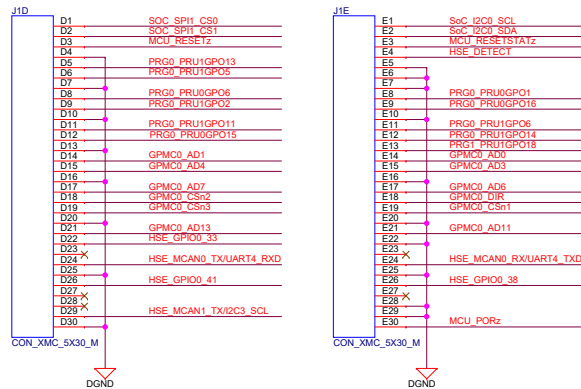
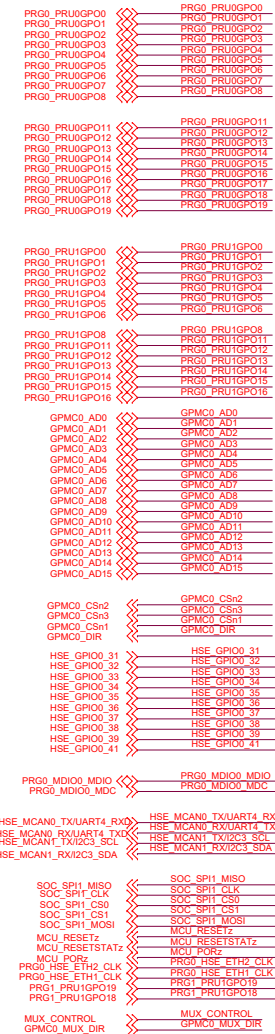
POWER_LED



PRG0 LED

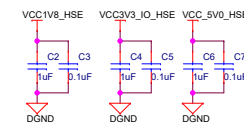


Off Page Connections

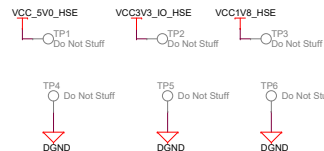


MUX SEL

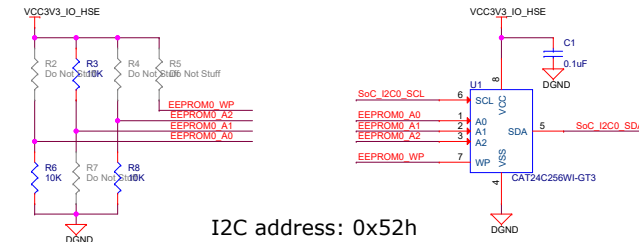
POWER DECAPS



Test Points



BOARD ID EEPROM



I2C address: 0x52h

SEL	INPUT/OUTPUT	FUNCTION - J11	FUNCTION - J19
L 2 - 3	nB1	An=nB1 SIGNALS ROUTED TO HEADERS	An=nB1 CS ROUTED TO BGA NAND
H 1 - 2	nB2	An=nB2 SIGNALS ROUTED TO NAND FLASH	An=nB1 CS ROUTED TO TSSOP NAND

Designed for TI by Mistral Solutions Pvt Ltd



Title HSE CONNECTOR

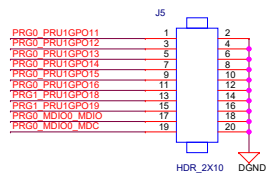
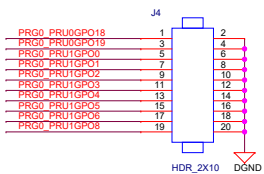
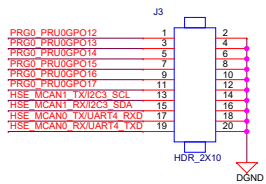
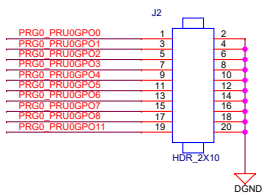
Size Variant Name = TMD864D02EVM

Date: Thursday, July 01, 2021

Sheet 4 of 7

Rev E1

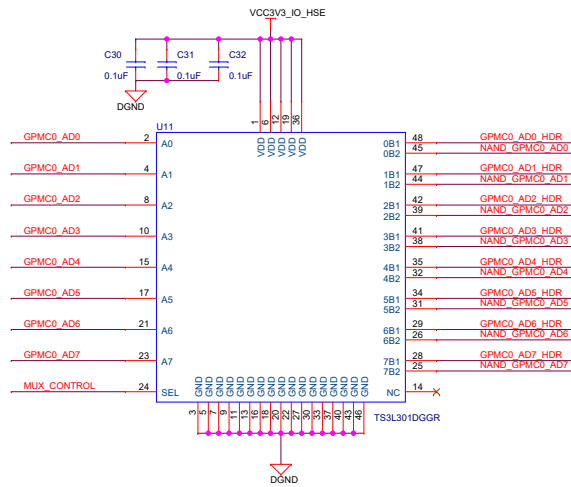
PRG SIGNALS HEADERS



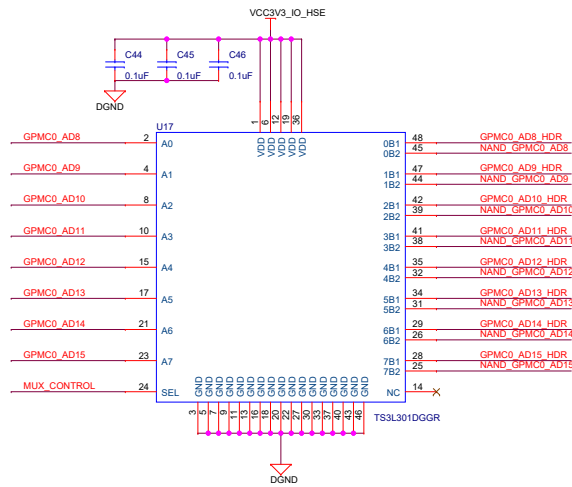
Off Page Connections

[illegible]

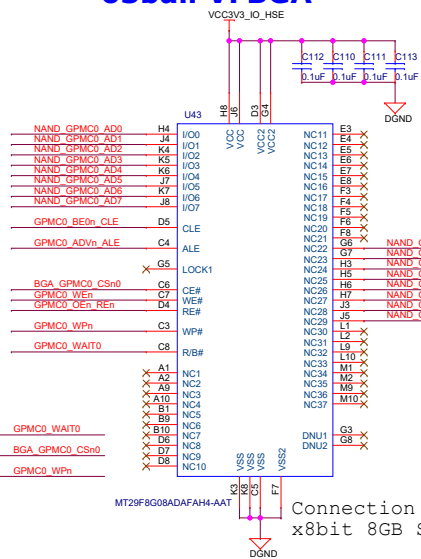
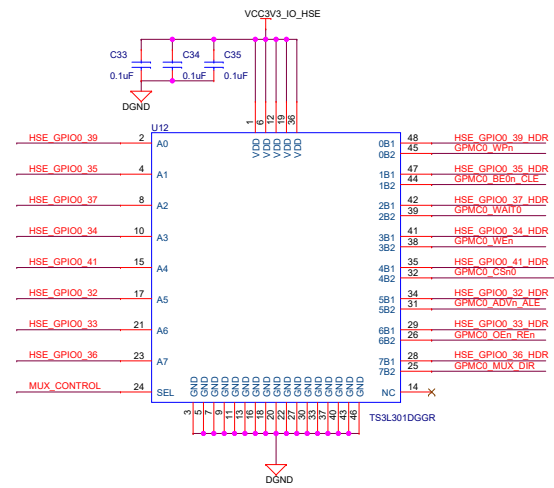
GPMC SIGNALS



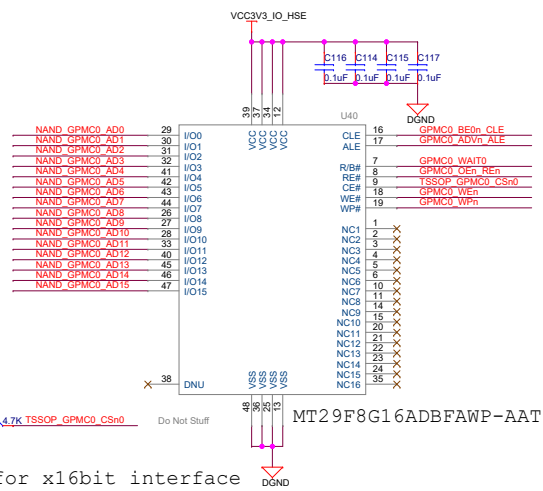
8GB SLC NAND FLASH
63ball VFBGA



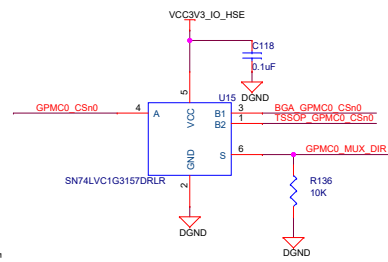
8GB SLC NAND FLASH - Socket for 48pin TSSOP



CAD NOTE:
GPMC Signals are Shared between BGA NAND & Socketed NAND with TSSOP package
Routing to be in-Line and Socket to be mounted on BOT



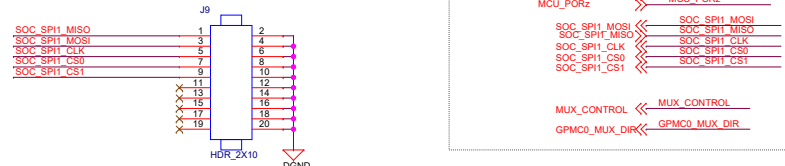
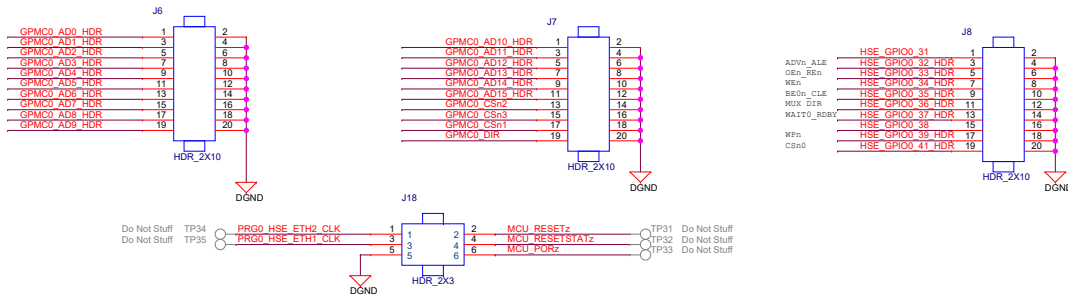
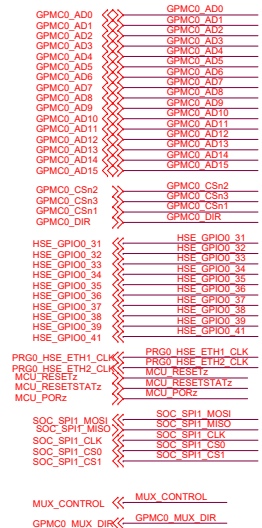
CS CNTRL MUX



CS - 1:2 MUX

SEL	CONDITION	FUNCTION
LOW	CS to BGA NAND FLASH	A-->B1 port
HIGH	CS to TSSOP NAND FLASH	A-->B2 port

Off Page Connections



Designed for TI by Mistral Solutions Pvt Ltd



Title	GPMC MUX AND NAND FLASH
-------	-------------------------

Size	
------	--

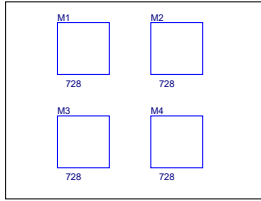
Date: Friday, July 02, 2021

Date:	Friday, July 02, 2021	Sheet	6	of	7
-------	-----------------------	-------	---	----	---

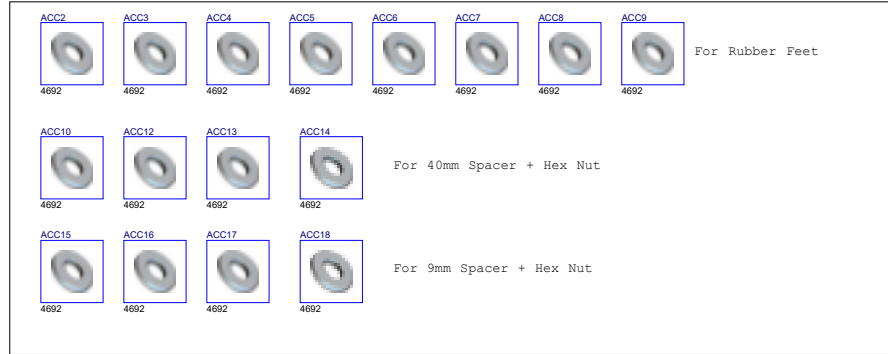
Rev

HARDWARE SCHEMATICS

RUBBER FEET



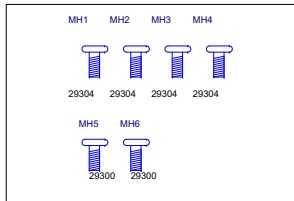
WASHER's



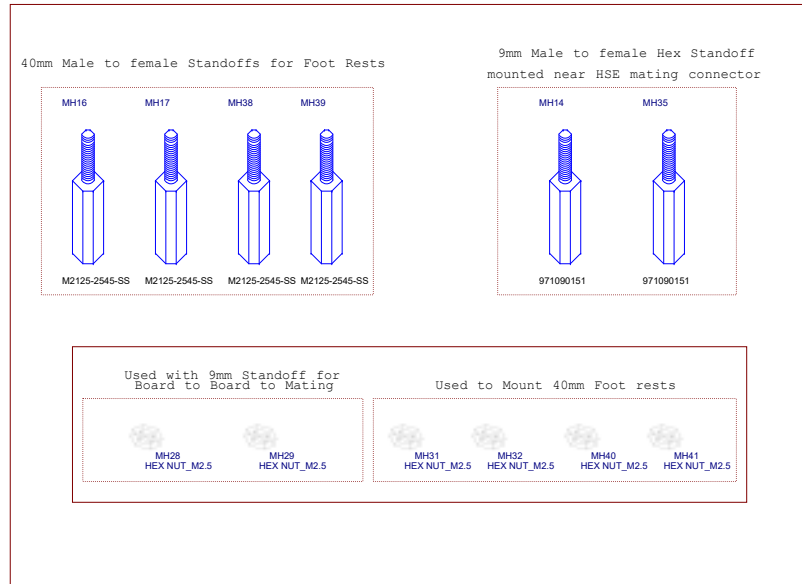
ASSEMBLY NOTES

1. All MSL components should be baked as per JEDEC standard.
2. PCB should be baked at 120 degree for 8 hours.
3. Board assembly must comply with workmanship standards. IPC-A-610 Class 2, unless otherwise specified.
4. These assemblies are ESD sensitive, ESD precautions shall be observed.
5. These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
6. Provide serial numbers to the assembled boards for identification.
7. The assembled board are wrapped in ESD Covers(individual) and packed securely before shipment.

SCREWS



STANDOFFs



LABELS

Board Serial No.



ORDERABLE PART NO



Assembly Revision



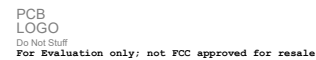
Orderable part number

Variant	Label Text
001	TMD564DC02EVM

FIDUCIALS



LOGOs



LOGOs



BARE PCB



Assembled PCB

Designed for TI by Mistral Solutions Pvt Ltd



Title HARDWARE SCHEMATIC

Size	Variant Name = TMD564DC02EVM	Rev
C		E1
Date:	Wednesday, July 07, 2021	Sheet 7 of 7